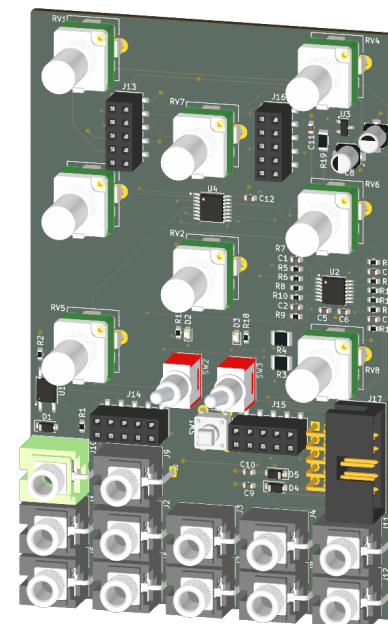


TOP ASSEMBLY

NOTE: ASSEMBLY MUST COMPLY WITH RoHS DIRECTIVE OF THE EUROPEAN UNION



TOP VIEW

Black And White TOP – Page 1/3

# DIALTONE SYNTHESIS

Sheet: Black And White TOP  
File: 200\_Plattform.kicad\_pcb

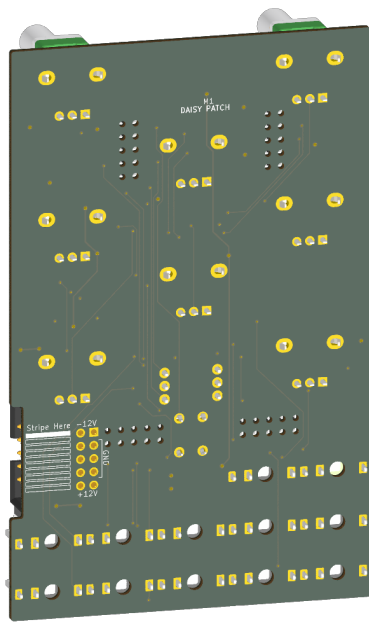
## Title: 200 Series Digital Audio Platform

Size: A4 Date: 2025-03-04

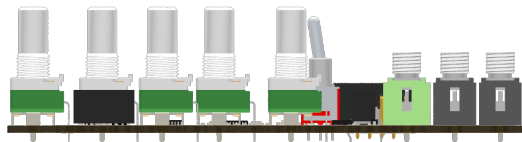
KiCad E.D.A. 9.0.0

Rev: A1

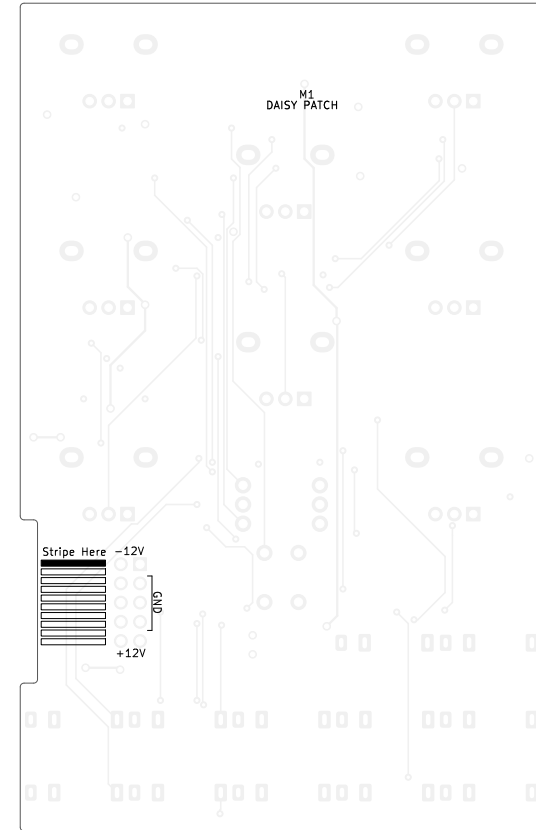
Id: /1



BOTTOM VIEW



SIDE VIEW



BOTTOM ASSEMBLY

NOTE: NO COMPONENTS ASSEMBLED ON BOTTOM

Black And White BOT – Page 2/3

**DIALTONE SYNTHESIS**

Sheet: Black And White BOT  
File: 200\_Plattform.kicad\_pcb

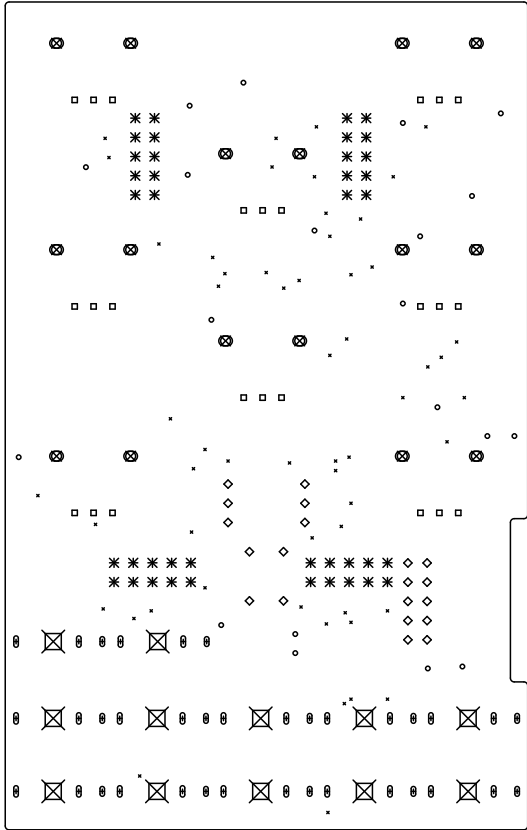
**Title: 200 Series Digital Audio Platform**

Size: A4 Date: 2025-03-04

KiCad E.D.A. 9.0.0

**Rev: A1**

Id: /1



Drill Map:

- 0.300mm / 0.0118" (56 holes)
- 0.600mm / 0.0236" (20 holes)
- + 0.600mm / 0.0236" (0 holes + 36 slots)
- ◻ 1.000mm / 0.0394" (24 holes)
- ◊ 1.100mm / 0.0433" (20 holes)
- ⊗ 1.300mm / 0.0512" (0 holes + 16 slots)
- \* 1.200mm / 0.0472" (40 holes) (not plated)
- ⊠ 3.000mm / 0.1181" (12 holes) (not plated)

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.21 mm	FR4 natural	4.5	0.02
In1.Cu	copper		0.015 mm		1	0
Dielectric 2	core	FR4	1.06 mm	FR4 natural	4.5	0.02
In2.Cu	copper		0.015 mm		1	0
Dielectric 3	prepreg	FR4	0.21 mm	FR4 natural	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

NOTE: STACKUP TABLE IS FOR REFERENCE.  
1 OZ OR GREATER COPPER MUST BE MAINTAINED ON OUTER LAYERS.  
0.5 OZ OR GREATER COPPER MUST BE MAINTAINED ON INNER LAYERS.  
FABRICATOR MAY OTHERWISE ADJUST LAYER THICKNESS TO CONFORM WITH STANDARD STACKUP.

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.6000 mm
Board overall dimensions:	69.0880 mm x 109.4740 mm		
Min track/spacing:	0.1524 mm / 0.1524 mm	Min hole diameter:	0.3000 mm
Copper Finish:	HAL lead-free	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

NOTE: PCB MUST CONFORM WITH THE ROHS DIRECTIVE OF THE EUROPEAN UNION

DIALTONE SYNTHESIS

Sheet: Black and White Fabrication  
File: 200\_Plattform.kicad\_pcb

Title: 200 Series Digital Audio Platform

Size: A4	Date: 2025-03-04	Rev: A1
KiCad E.D.A. 9.0.0		Id: /1